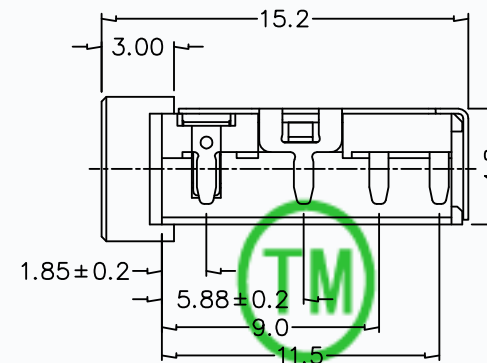
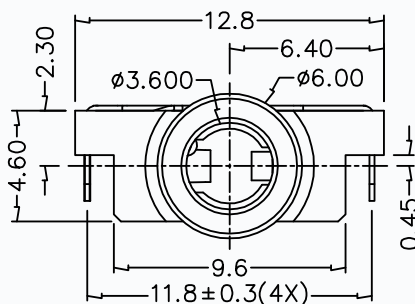
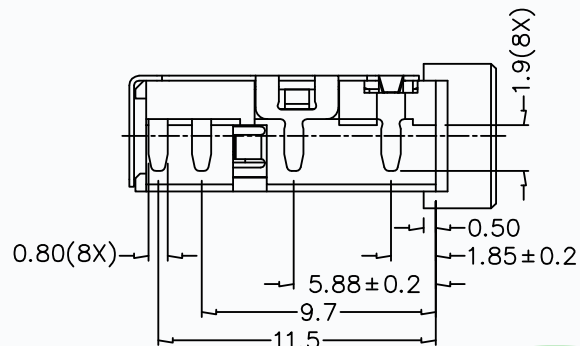
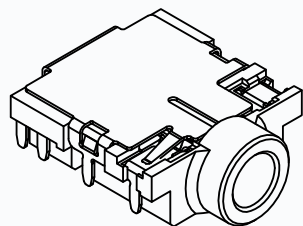
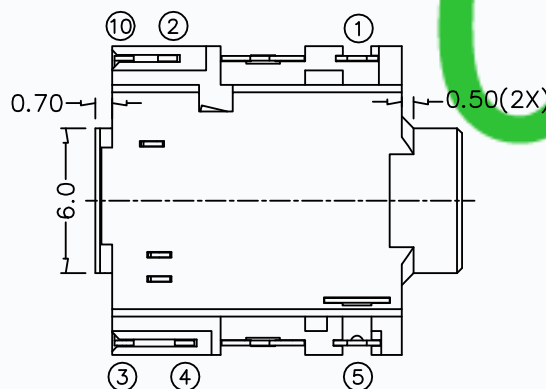


CAD FILE:



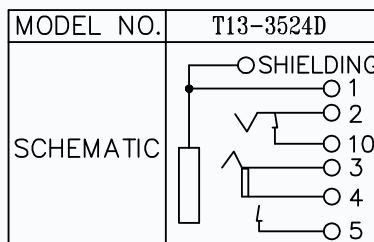
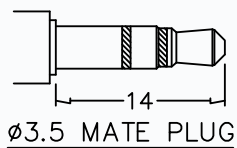
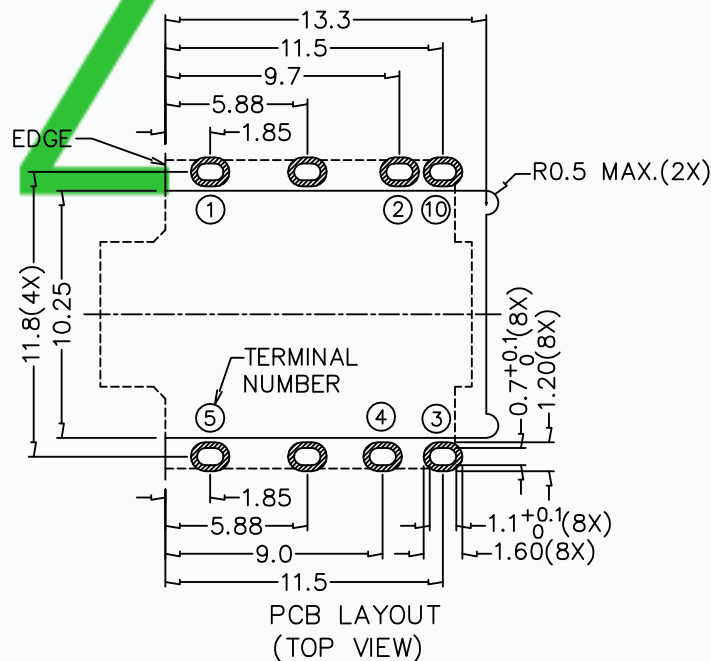
CMTDDZ



*** MATERIAL**

- TERMINAL 1 : COPPER ALLOY
- TERMINAL 2 : COPPER ALLOY
- TERMINAL 3 : COPPER ALLOY
- TERMINAL 4 : COPPER ALLOY
- TERMINAL 5 : COPPER ALLOY
- TERMINAL 10 : COPPER ALLOY
- SHIELD : COPPER ALLOY
- HOUSING : PA6T

PCB EDGE



APPD.	DESCRIPTIONS OF REVISION	TOLERANCE UNLESS SPECIFIED	THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF DONGGUAN TIANDU ELECTRONICS CO.,LTD. AND SHALL NOT BE REPRODUCED. COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF DONGGUAN TIANDU ELECTRONICS CO., LTD.	TITLE : 3.5mm SMD PHONE JACK	UNIT : mm	DRWG NO.: CMTDDZ-T13-3524-00		
		WITHIN 1.5mm : ±0.1mm		MODEL: T13-3524D	SCALE: 3:1	DWN.	ERIC	2013-6-17
		OVER 1.5mm : ±0.2mm		CMTDDZ 东莞市田都电子有限公司		CHK'D	MAIKO	2013-6-17
				DONGGUAN TIANDU ELECTRONICS CO.,LTD.		APPD.	Coco	2013-6-17